Switching Diode, High Voltage, High Temperature

BASH19L Series

Features

- 175°C T_{J(MAX)} Rated for High Temperature, Mission Critical Applications
- NSV Prefixes for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Continuous Reverse Voltage BASH19 BASH20 BASH21	V _R	120 200 250	Vdc
Repetitive Peak Reverse Voltage BASH19 BASH20 BASH21	V _{RRM}	120 200 250	Vdc
Continuous Forward Current	lF	200	mAdc
Peak Forward Surge Current (1/2 Cycle, Sine Wave, 60 Hz)	I _{FSM}	2	А
Repetitive Peak Forward Current (Pulse Train: T _{ON} = 1 s, T _{OFF} = 0.5 s)	I _{FRM}	0.6	Α
Junction and Storage Temperature Range	T _J , T _{stg}	-55 to +175	°C
Electrostatic Discharge	ESD	HM < 500	V
		MM < 400	V

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.



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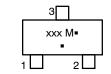
www.onsemi.com

HIGH VOLTAGE SWITCHING DIODE



MARKING DIAGRAM





SOT-23 (TO-236) CASE 318 STYLE 8

AD7 = BASH19L
AC7 = BASH20L
AA7 = BASH21L
M = Date Code
• = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

1

BASH19L Series

THERMAL CHARACTERISTICS

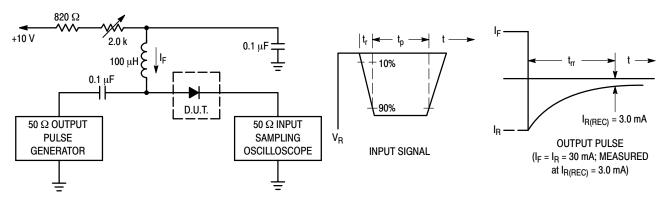
Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board (Note 1) T _A = 25°C	P _D	300	mW mW/°C
Derate above 25°C		1.0	IIIVV/ G
Thermal Resistance Junction-to-Ambient (SOT-23)	$R_{\theta JA}$	340	°C/W
Total Device Dissipation Alumina Substrate (Note 2) T _A = 25°C	P _D	400	mW
Derate above 25°C		2.4	mW/°C
Thermal Resistance Junction-to-Ambient	$R_{\theta JA}$	250	°C/W
Junction and Storage Temperature Range	T _J , T _{stg}	-55 to +175	°C

- 1. FR-5 = $1.0 \times 0.75 \times 0.062$ in.
- 2. Alumina = $0.4 \times 0.3 \times 0.024$ in. 99.5% alumina.

ELECTRICAL CHARACTERISTICS ($T_A = 25$ °C unless otherwise noted)

Characteristic	Characteristic			Max	Unit
Reverse Voltage Leakage Current		I _R			μAdc
(V _R = 100 Vdc)	BASH19		-	0.1	
(V _R = 150 Vdc)	BASH20		-	0.1	
(V _R = 200 Vdc)	BASH21		_	0.1	
$(V_R = 100 \text{ Vdc}, T_J = 175^{\circ}\text{C})$	BASH19		_	100	
(V _R = 150 Vdc, T _J = 175°C)	BASH20		_	100	
(V _R = 200 Vdc, T _J = 175°C)	BASH21		-	100	
Reverse Breakdown Voltage		V _(BR)			Vdc
(I _{BR} = 100 μAdc)	BASH19	, ,	120	_	
(I _{BR} = 100 μAdc)	BASH20		200	_	
(I _{BR} = 100 μAdc)	BASH21		250	-	
Forward Voltage		V _F			Vdc
(I _F = 100 mAdc)			_	1.0	
(I _F = 200 mAdc)			-	1.25	
Diode Capacitance (V _R = 0, f = 1.0 MHz)		C _D	-	5.0	pF
Reverse Recovery Time ($I_F = I_R = 30 \text{ mAdc}$, $I_{R(REC)} = 3.0 \text{ mA}$	Adc, R _L = 100)	t _{rr}	-	50	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.



Notes: 1. A 2.0 $k\Omega$ variable resistor adjusted for a Forward Current (I_F) of 30 mA.

- 2. Input pulse is adjusted so $I_{R(peak)}$ is equal to 30 mA.
- 3. $t_p \gg t_{rr}$

Figure 1. Recovery Time Equivalent Test Circuit

BASH19L Series

TYPICAL CHARACTERISTICS

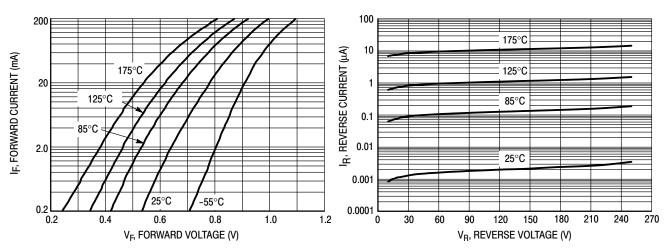


Figure 2. Forward Voltage

Figure 3. Leakage Current

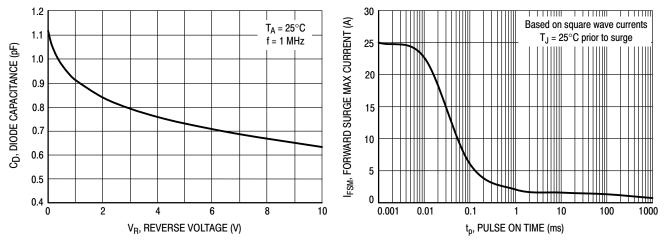


Figure 4. Capacitance

Figure 5. Forward Surge Current

BASH19L Series

ORDERING INFORMATION

Device	Package	Shipping [†]
BASH19LT1G	SOT-23 (Pb-Free)	3000 / Tape & Reel
NSVBASH19LT1G*	SOT-23 (Pb-Free)	3000 / Tape & Reel
BASH20LT1G	SOT-23 (Pb-Free)	3000 / Tape & Reel
NSVBASH20LT1G*	SOT-23 (Pb-Free)	3000 / Tape & Reel
BASH21LT1G	SOT-23 (Pb-Free)	3000 / Tape & Reel
NSVBASH21LT1G*	SOT-23 (Pb-Free)	3000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
*NSV Prefixes for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q101 Qualified and PPAP Capable – release available upon request.



SOT-23 (TO-236) CASE 318-08 **ISSUE AS**

DATE 30 JAN 2018

SCALE 4:1 D - 3X b

TOP VIEW







RECOMMENDED SOLDERING FOOTPRINT



DIMENSIONS: MILLIMETERS

NOTES:

- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH.
 MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL
- 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH,

	PROT	RUSIONS, OR GATE BURRS.	
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	MILLIMETERS				INCHES	
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.039	0.044
A1	0.01	0.06	0.10	0.000	0.002	0.004
b	0.37	0.44	0.50	0.015	0.017	0.020
С	0.08	0.14	0.20	0.003	0.006	0.008
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.080
L	0.30	0.43	0.55	0.012	0.017	0.022
L1	0.35	0.54	0.69	0.014	0.021	0.027
HE	2.10	2.40	2.64	0.083	0.094	0.104
Т	0°		10°	0°		10°

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code

= Date Code

= Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

STYLE 1 THRU 5: CANCELLED	STYLE 6: PIN 1. BASE 2. EMITTER 3. COLLECTOR	STYLE 7: PIN 1. EMITTER 2. BASE 3. COLLECTOR	STYLE 8: PIN 1. ANODE 2. NO CONNECTION 3. CATHODE
OT (1 F O			

SOT-23 (TO-236)

STYLE 9:	STYLE 10:	STYLE 11:	STYLE 12:	STYLE 13:	STYLE 14:
PIN 1. ANODE	PIN 1. DRAIN	PIN 1. ANODE	PIN 1. CATHODE	PIN 1. SOURCE	PIN 1. CATHODE
ANODE	SOURCE	CATHODE	CATHODE	2. DRAIN	2. GATE
CATHODE	3. GATE	CATHODE-ANODE	ANODE	3. GATE	ANODE

STYLE 15:	STYLE 16:	STYLE 17:	STYLE 18:	STYLE 19:	STYLE 20:
PIN 1. GATE	PIN 1. ANODE	PIN 1. NO CONNECTION	PIN 1. NO CONNECTION	PIN 1. CATHODE	PIN 1. CATHODE
CATHODE	CATHODE	2. ANODE	CATHODE	2. ANODE	ANODE
ANODE	CATHODE	CATHODE	ANODE	CATHODE-ANOD	E 3. GATE

STYLE 21:	STYLE 22:	STYLE 23:	STYLE 24:	STYLE 25:	STYLE 26:
PIN 1. GATE	PIN 1. RETURN	PIN 1. ANODE	PIN 1. GATE	PIN 1. ANODE	PIN 1. CATHODE
SOURCE	OUTPUT	2. ANODE	2. DRAIN	2. CATHODE	2. ANODE
3 DRAIN	3 INPLIT	3 CATHODE	3. SOURCE	3. GATE	NO CONNECTION

STYLE 27: PIN 1. CATHODE 2. CATHODE 3. CATHODE	STYLE 28: PIN 1. ANODE 2. ANODE 3. ANODE	
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DESCRIPTION:

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